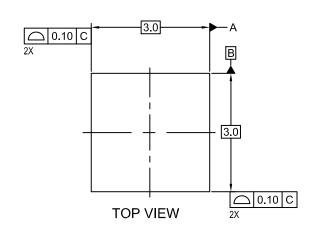
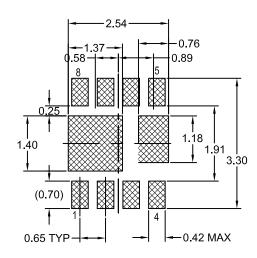
WDFN8 3x3, 0.5P CASE 511DF ISSUE O

**DATE 31 JUL 2016** 



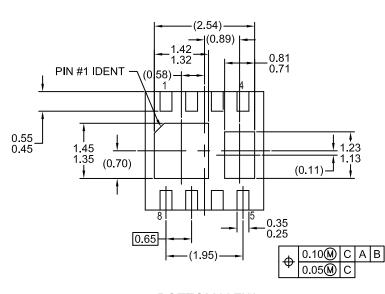


0.05 C 0.05 O SIDE VIEW C SIDE VIEW

RECOMMENDED LAND PATTERN (NSMD PAD TYPE)



- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VEEC, DATED 11/2001
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994



**BOTTOM VIEW** 

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